

ABSTRACT

The invention provides a structure of Surface Mount Device Light Emitting Diode (SMD LED), which includes a printed circuit board with a
5 metal reflection cup set concavely on the printed circuit board. Besides, at least one LED chip is bonded to the metal reflection cup and electrically connected to the printed circuit board. In addition, an encapsulant is utilized to cover the LED chip and also protrudes from the surface of the printed circuit board for forming a desired shape. The encapsulant of the invention can be
10 directly molded on the printed circuit board and integrally formed in any shape so that the encapsulant will not come off the printed circuit board in any circumstances and that the metal reflection cup can let the light to be fully reflected.